

Abstract of the Disclosure

Sub 8.17

A plurality of electronic components having conductive connecting members are surface-mounted to a target surface of a circuit board in a plurality of specified terminal-forming areas each having terminal parts. An anisotropic conductive layer is formed on this target surface so as to span these terminal-forming areas, and the plurality of electronic components are placed on this anisotropic conductive layer individually above the plurality of terminal-forming areas. As the layer is heated, these electronic components are pressed against the layer such that the conductive connecting members of the electronic components become attached to and electrically conductive with corresponding ones of the terminal parts on the circuit board. The anisotropic conductive layer remains electrically insulative elsewhere.

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